

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)MAX}$	I_D
650V	100mΩ@10V	30A

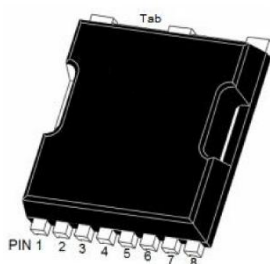
Feature

- Fast Switching
- Low Gate Charge and Rdson

Application

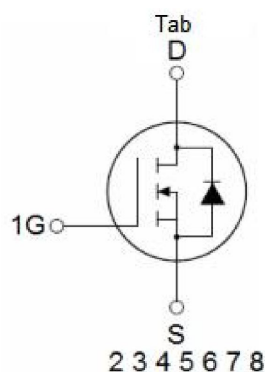
- PWM Application
- Hard switched and high frequency circuits
- Power Management

Package

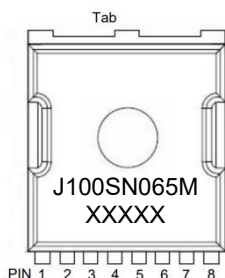


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Circuit diagram



Marking



Absolute maximum ratings ($T_a=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	650	V
Gate-Source Voltage	V_{GS}	± 30	V
Continuous Drain Current ($T_c=25^\circ\text{C}$)	I_D	30	A
Continuous Drain Current ($T_c=100^\circ\text{C}$)	$I_{D(100^\circ\text{C})}$	20	A
Pulsed Drain Current	I_{DM}	120	A
Power Dissipation ($T_c=25^\circ\text{C}$)	P_D	193	W
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	0.65	$^\circ\text{C/W}$
Single pulse avalanche Energy ¹⁾	E_{AS}	362	mJ
Junction Temperature	T_J	150	$^\circ\text{C}$
Storage Temperature Range	T_{STG}	-55 ~ +150	$^\circ\text{C}$

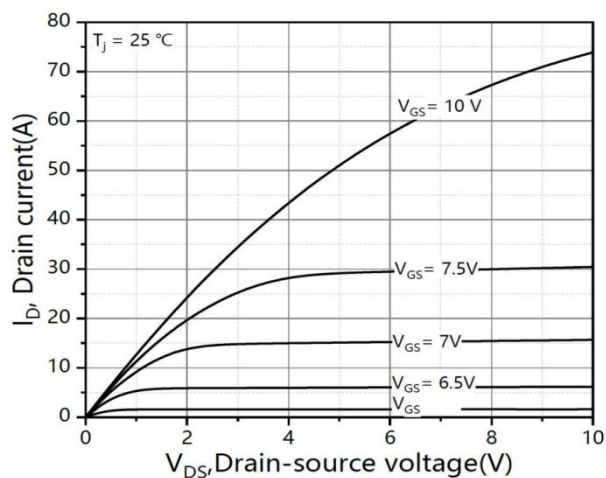
Electrical characteristics ($T_a=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =250μA	650			V
Zero gate voltage drain current	I _{DSS}	V _{DS} =520V, V _{GS} =0V			1	μA
Gate-body leakage current	I _{GSS}	V _{GS} =±30V, V _{DS} =0V			±100	nA
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	2.5	3.5	4.5	V
Drain-source on-resistance	R _{DS(on)}	V _{GS} =10V, I _D =30A		85	100	mΩ
Dynamic characteristics ²⁾						
Input Capacitance	C _{iss}	V _{DS} =50V, V _{GS} =0V, f =100kHz		2618		pF
Output Capacitance	C _{oss}			136		
Reverse Transfer Capacitance	C _{rss}			4.1		
Total Gate Charge	Q _g	V _{DS} =400V, V _{GS} =10V, I _D =40A		54		nC
Gate-Source Charge	Q _{gs}			19		
Gate-Drain Charge	Q _{gd}			21		
Turn-on delay time	t _{d(on)}	V _{DS} =400V, V _{GS} =10V, I _D =40A, R _G =2Ω		35		nS
Turn-on rise time	t _r			152		
Turn-off delay time	t _{d(off)}			63		
Turn-off fall time	t _f			48		
Source-Drain Diode characteristics						
Diode Forward voltage	V _{SD}	V _{GS} =0V, I _S =1A, T _J =25℃			1.2	V
Diode Forward Current	I _S				30	A
Reverse Recovery Time	t _{rr}	I _S =40A ,di/dt =100A/μs, T _J =25℃		148		nS
Reverse Recovery Charge	Q _{rr}			1.2		μC

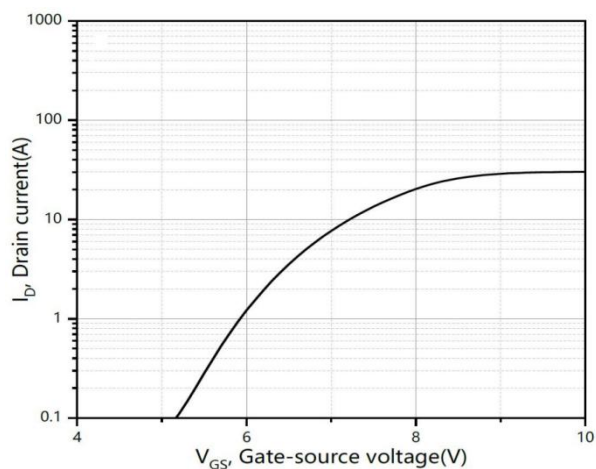
Notes:

- 1) The test condition is $V_{DD}=50V, V_{GS}=10V, L=0.5mH, R_G=25\Omega$
- 2) Guaranteed by design, not subject to production.

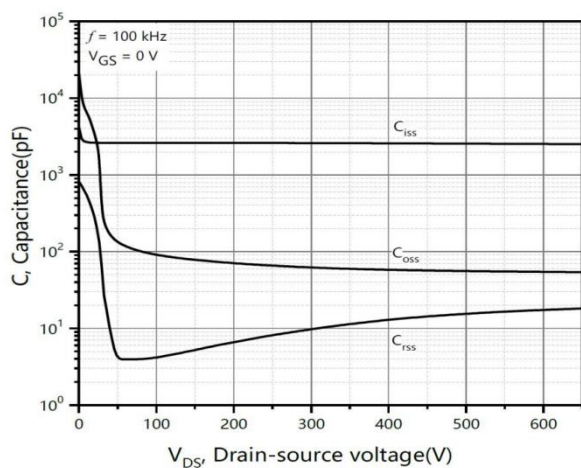
Typical Characteristics



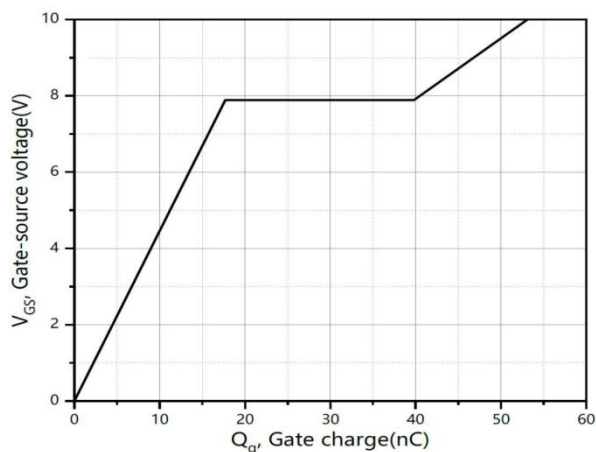
Typ. output characteristics $T_J=25^\circ\text{C}$



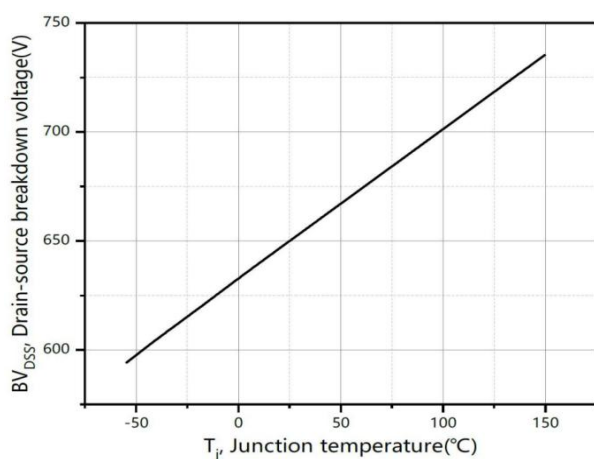
Typ. transfer characteristics



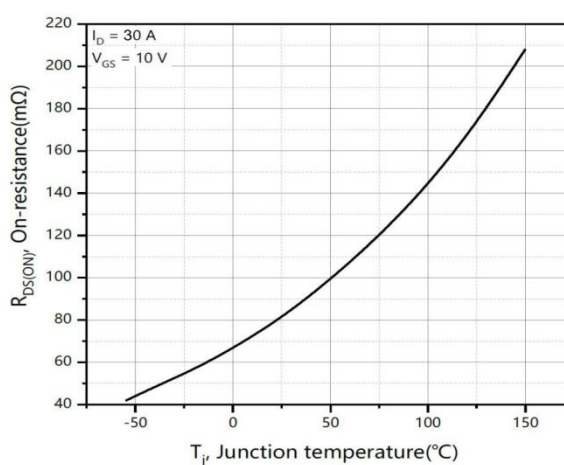
Typ. capacitances



Typ. gate charge

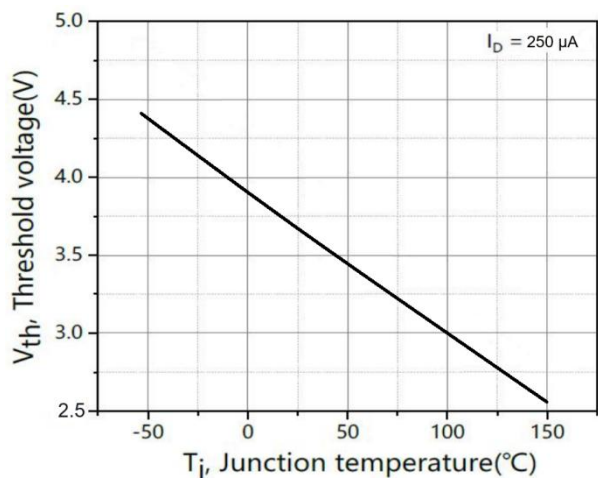


Drain-source breakdown voltage

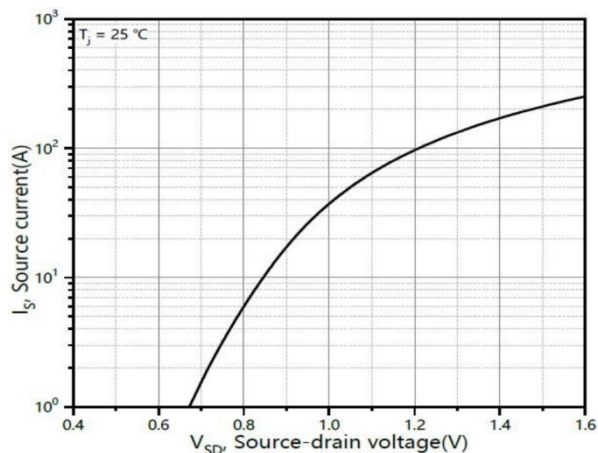


Drain-source on-state resistance

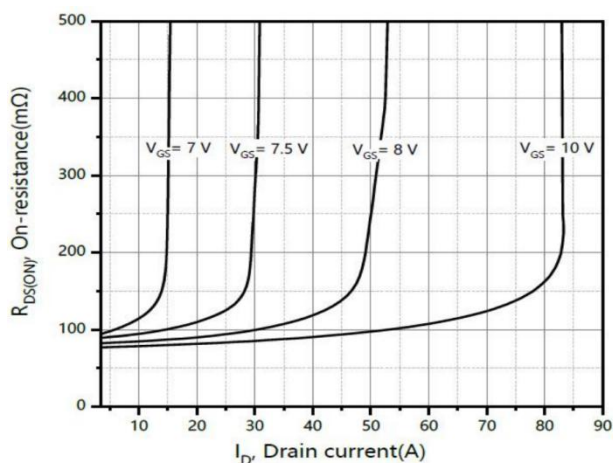
Typical Characteristics



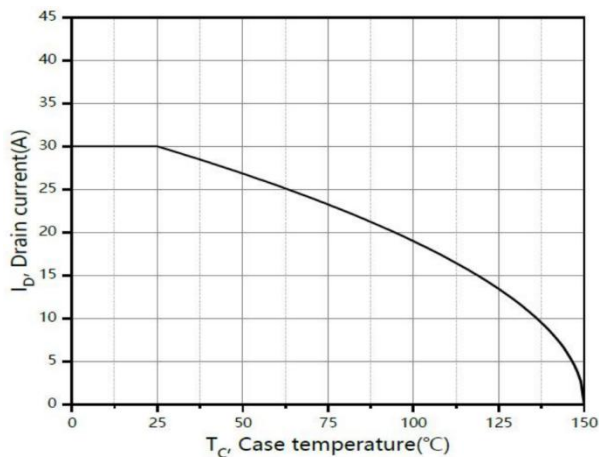
Threshold voltage



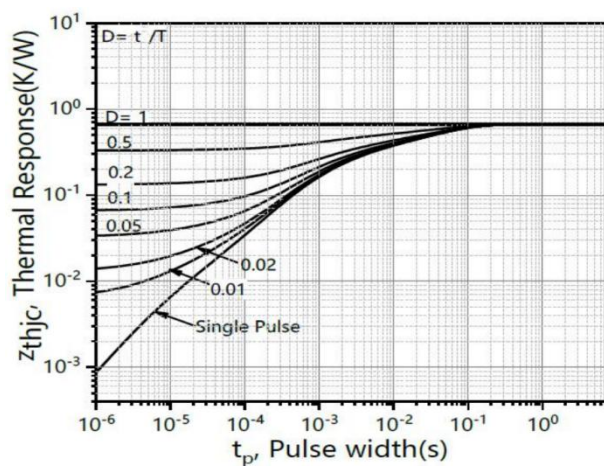
Forward characteristic of body diode



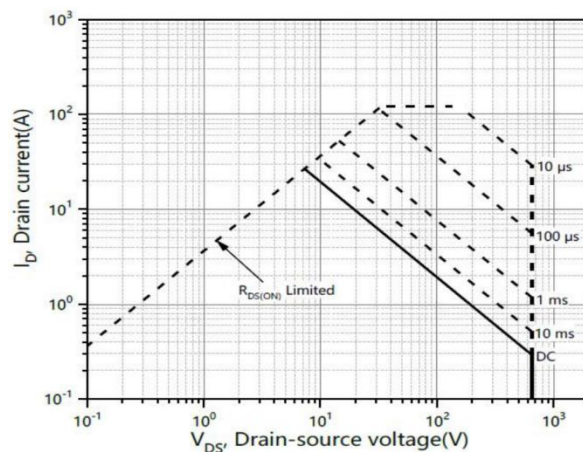
Drain-source on-state resistance



Drain current

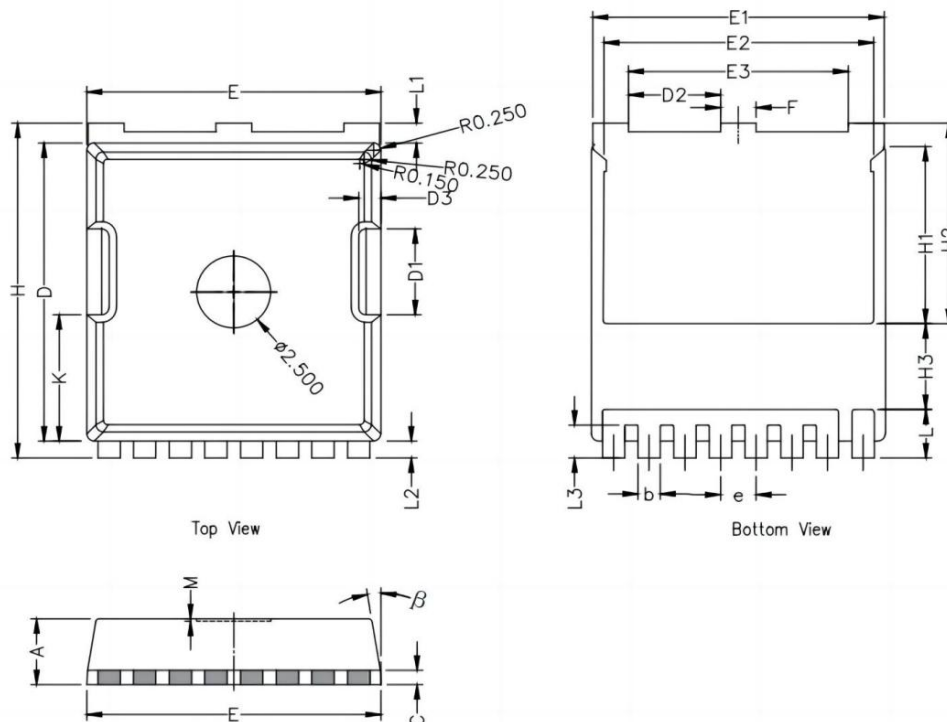


Max. transient thermal impedance



Safe operation area $T_c=25^{\circ}C$

TOLL Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
b	0.650	0.850	0.026	0.033
C	0.508 REF.		0.020 REF.	
D	10.250	10.550	0.404	0.415
D1	2.850	3.150	0.112	0.124
E	9.750	10.050	0.384	0.396
E1	9.650	9.950	0.380	0.392
E2	8.950	9.250	0.352	0.364
E3	7.250	7.550	0.285	0.297
e	1.200 BSC.		0.047 BSC.	
F	1.050	1.350	0.041	0.053
H	11.550	11.850	0.455	0.467
H1	6.030	6.330	0.237	0.249
H2	6.850	7.150	0.270	0.281
H3	3.000 BSC.		0.118 BSC.	
L	1.550	1.850	0.061	0.073
L1	0.550	0.850	0.022	0.033
L2	0.450	0.750	0.018	0.030
M	0.080 REF.		0.003 REF.	
β	8°	12°	8°	12°
K	4.250	4.550	0.167	0.179